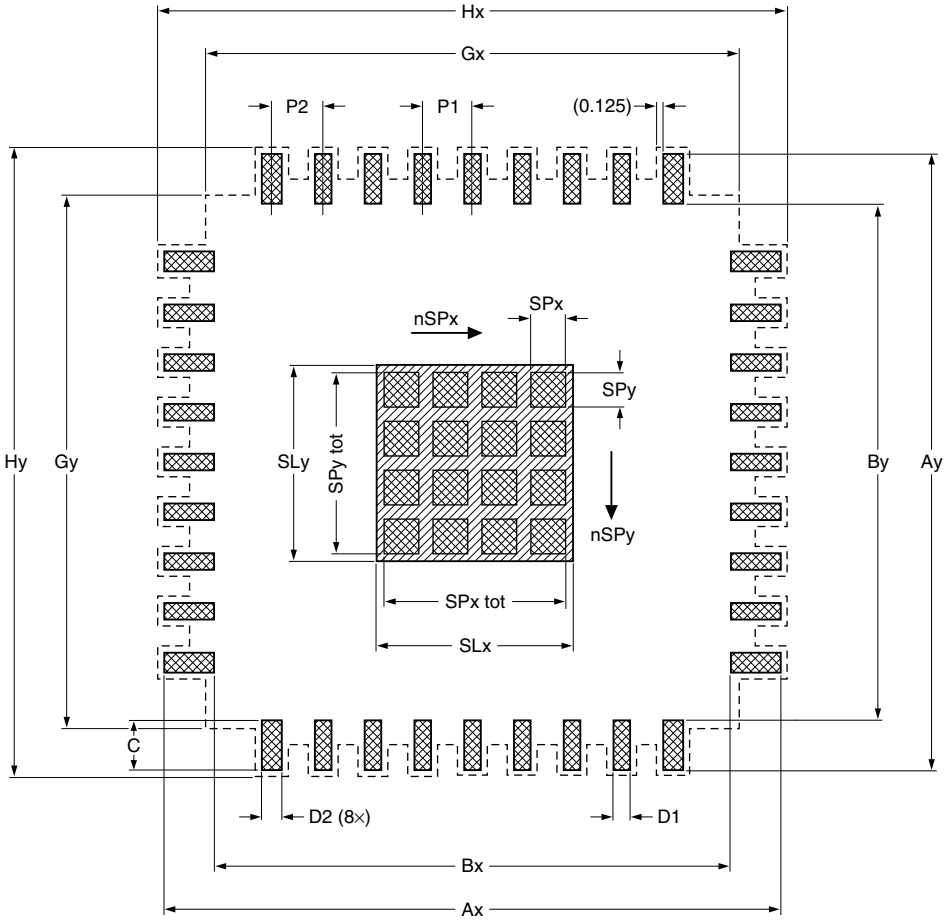
Reflow soldering footprint

Footprint information for reflow soldering of HLQFP256 package **SOT1128-1**



Generic footprint pattern

Refer to the package outline drawing for actual layout

solder land

solder paste

occupied area

SPx	SPy	nSPx	nSPy
0.900	0.900	6	6

Dimensions in mm

P1	P2	Ax	Ay	Bx	By	C	D1	D2	Gx	Gy	Hx	Hy	SLx	SLy	SPx tot	SPy tot
0.400	0.430	31.300	31.300	28.300	28.300	1.500	0.240	0.300	28.500	28.500	31.550	31.550	7.830	7.830	7.700	7.700

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